

ABSTRACT OF THE DISCLOSURE

A leadframe is disclosed comprising a plurality of leads. The leads of the leadframe extend radially from a first end to a second end such that a portion of each lead has a generally arcuate shape. The first end is for coupling with a printed circuit board. The second end is for coupling the a semiconductor die. Alternatively, the leads have a plurality of segments. Each lead has at least three segments disposed between the first end and the second end. The segments forming the leads are disposed such that each lead generally has an arcuate shape. The segments each have substantially the same length, or can have varying lengths. An integrated circuit package is also disclosed including a leadframe having a plurality of leads, at least one semiconductor die coupled with the leads, and an insulating enclosure encapsulating the die and a portion of the leadframe. The leads each extend radially from a first end to a second end such that each lead has a generally arcuate shape. The leads can also have at least three segments disposed between the first end and the second end.

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